

P-Channel Enhancement-Mode Vertical DMOS FETs

Ordering Information

BV _{DSS} /	R _{DS(ON)}	V _{GS(th)}	I _{D(ON)}	Order Numb	er / Package
BV _{DGS}	(max)	(max)	(min)	TO-243AA*	Die [†]
-200V	12Ω	-2.4V	-0.75A	TP2520N8	_
-220V	12Ω	-2.4V	-0.75A	TP2522N8	TP2522ND

^{*} Same as SOT-89. Product supplied on 2000 piece carrier tape reels.

Features

- Low threshold -2.4V max.
- High input impedance
- Low input capacitance 125pF max.
- Fast switching speeds
- Low on resistance
- Free from secondary breakdown
- Low input and output leakage
- Complementary N- and P-channel devices

Applications

- ☐ Logic level interfaces ideal for TTL and CMOS
- Solid state relays
- Battery operated systems
- Photo voltaic drives
- Analog switches
- General purpose line drivers
- □ Telecom switches

Absolute Maximum Ratings

Drain-to-Source Voltage	BV_{DSS}
Drain-to-Gate Voltage	BV _{DGS}
Gate-to-Source Voltage	± 20V
Operating and Storage Temperature	-55°C to +150°C
Soldering Temperature*	300°C

^{*} Distance of 1.6 mm from case for 10 seconds.

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Product marking for TO-243AA

TP5C*

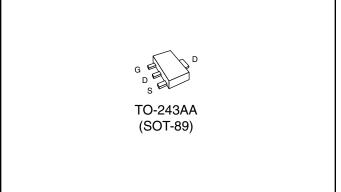
Where *=2-week alpha date code

Low Threshold DMOS Technology

These low threshold enhancement-mode (normally-off) transistors utilize a vertical DMOS structure and Supertex's well-proven silicon-gate manufacturing process. This combination produces devices with the power handling capabilities of bipolar transistors and with the high input impedance and positive temperature coefficient inherent in MOS devices. Characteristic of all MOS structures, these devices are free from thermal runaway and thermally-induced secondary breakdown.

Supertex's vertical DMOS FETs are ideally suited to a wide range of switching and amplifying applications where very low threshold voltage, high breakdown voltage, high input impedance, low input capacitance, and fast switching speeds are desired.

Package Option



Note: See Package Outline section for dimensions

[†]MIL visual screening available.

Thermal Characteristics

Package	I _D (continuous)*	I _D (pulsed)	Power Dissipation @ T _A = 25°C	θ _{jc} °C/W	$ heta_{ja}$ $^{\circ}$ C/W	I _{DR} *	I _{DRM}
TO-243AA	-260mA	-2.0A	1.6W	15	78 [†]	-260mA	-2.0A

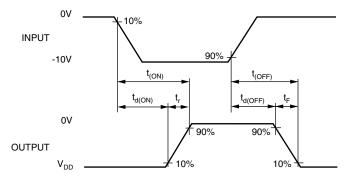
 $^{^{\}star}$ $\rm I_{\rm D}$ (continuous) is limited by max rated $\rm T_{\rm j}.$

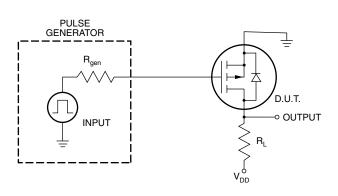
Electrical Characteristics (@ 25°C unless otherwise specified)

Symbol	Parameter		Min	Тур	Max	Unit	Conditions	
BV _{DSS}	Drain-to-Source Breakdown Voltage	TP2522	-220			V	$V_{GS} = 0V, I_{D} = -2mA$	
		TP2520	-200				VGS - 0V, ID - 21111	
V _{GS(th)}	Gate Threshold Voltage		-1.0		-2.4	V	$V_{GS} = V_{DS}$, $I_D = -1 \text{mA}$	
$\Delta V_{GS(th)}$	Change in V _{GS(th)} with Temperature				4.5	mV/°C	$V_{GS} = V_{DS}$, $I_D = -1 \text{mA}$	
I _{GSS}	Gate Body Leakage				-100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
I _{DSS}	Zero Gate Voltage Drain Current				-10	μΑ	$V_{GS} = 0V$, $V_{DS} = Max$ Rating	
					-1.0	mA	$V_{GS} = 0V$, $V_{DS} = 0.8$ Max Rating $T_A = 125$ °C	
I _{D(ON)}	ON-State Drain Current		-0.25	-0.7		Α	$V_{GS} = -4.5V, V_{DS} = -25V$	
			-0.75	-2.1			$V_{GS} = -10V, V_{DS} = -25V$	
R _{DS(ON)}	R _{DS(ON)} Static Drain-to-Source ON-State Resistance			10	15	Ω	$V_{GS} = -4.5V, I_{D} = -100mA$	
				8.0	12		$V_{GS} = -10V, I_D = -200mA$	
$\Delta R_{DS(ON)}$	Change in R _{DS(ON)} with Temperature				1.7	%/°C	$V_{GS} = -10V, I_D = -200mA$	
G _{FS}	Forward Transconductance		100	250		mʊ	$V_{DS} = -25V, I_{D} = -200mA$	
C _{ISS}	Input Capacitance			75	125			
C _{OSS}	Common Source Output Capacitance			20	85	pF	$V_{GS} = 0V$, $V_{DS} = -25V$ f = 1 MHz	
C _{RSS}	Reverse Transfer Capacitance			10	35			
t _{d(ON)}	Turn-ON Delay Time				10	ns $V_{DD} = -25V,$ $I_{D} = -0.75A,$ $R_{CEN} = 25\Omega$		
t _r	Rise Time				15			
t _{d(OFF)}	Turn-OFF Delay Time				20		$R_{GFN} = 25\Omega$	
t _f	Fall Time				15		GEN	
V _{SD}	Diode Forward Voltage Drop				-1.8	V	$V_{GS} = 0V, I_{SD} = -0.5A$	
t _{rr}	Reverse Recovery Time			300		ns	$V_{GS} = 0V, I_{SD} = -0.5A$	

Notes:

Switching Waveforms and Test Circuit



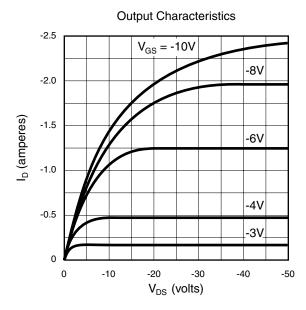


 $^{^{\}dagger}$ Mounted on FR5 board, 25mm x 25mm x 1.57mm. Significant $P_{_{D}}$ increase possible on ceramic substrate.

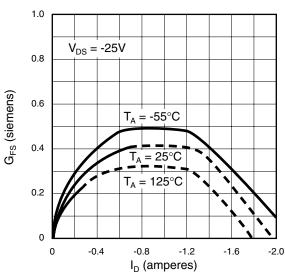
 $^{1.} All\ D.C.\ parameters\ 100\%\ tested\ at\ 25^{\circ}C\ unless\ otherwise\ stated.\ (Pulse\ test:\ 300\mu s\ pulse,\ 2\%\ duty\ cycle.)$

^{2.}All A.C. parameters sample tested.

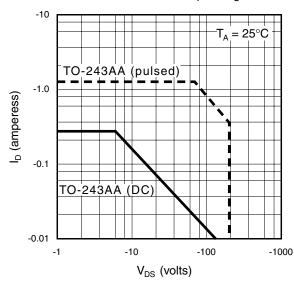
Typical Performance Curves



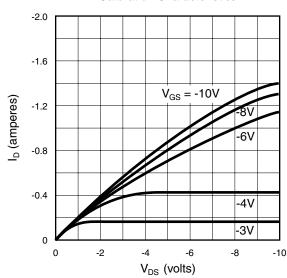
Transconductance vs. Drain Current



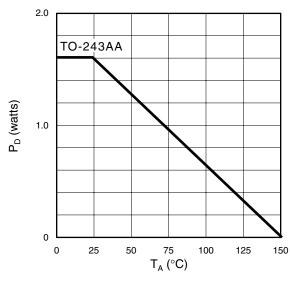
Maximum Rated Safe Operating Area



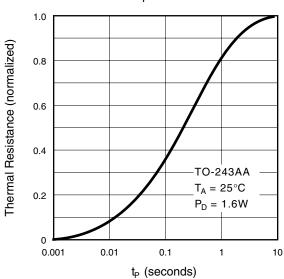
Saturation Characteristics



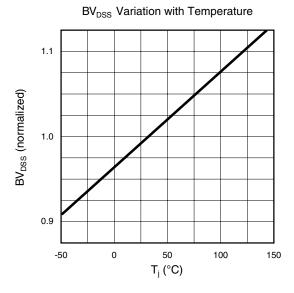
Power Dissipation vs. Ambient Temperature

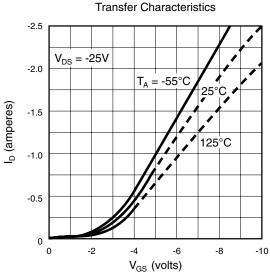


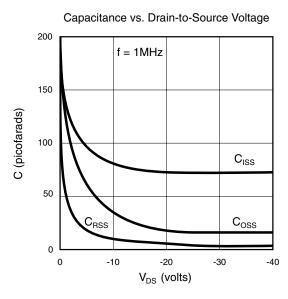
Thermal Response Characteristics

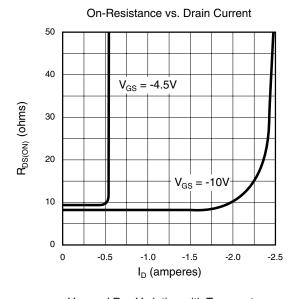


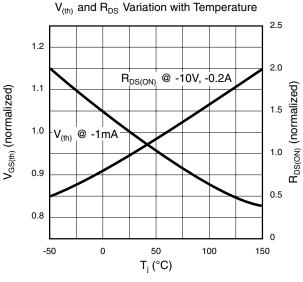
Typical Performance Curves

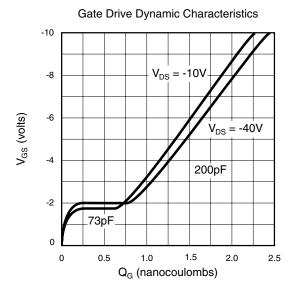












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